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The following subjects are proposals for possible presentations given by our speakers (for keynote speaking, paper sessions & poster sessions).

**Please note: This is not an agenda nor a ranking for the workshop.**

- Machine Learning (ML) & Artificial Intelligence (AI) in our industry (for testing)
- WLCSP, module technical challenges for 5G technology (28GHz ~ 44GHz)
- Bump, micro-bump & copper pillars, WLCSP challenges & solutions
- New challenges for probing & test for automotive (new car technologies; e drive & hybrid / autonomous driving cars)
- Automotive wafer test with tri-temp. and with high current
- Frame probing with temperatures
- Challenges for probing over active area
- New probe card solutions
- Less probe mark damages but good contact – depthness control (control the probing overdrive) – low force probing
- Probe cleaning technologies / Probe tip resistance / burn on probe tip / probe cleaning at temp. probing
- Efficiency during testing by optimized probe card design
- Ultra-fine pitch probing solution
- Probing on Cu- pads
- Highest power
- RF testing
- Probe mark inspection (PMI)
- Post probe insp. vs. inline PMI
- Inline process control (tip diameter, Cres, imprint etc.)
- Know Good Dies
- Hot & Cold temperature test
- MEMS & sensor test
- Wafer level burn-in
- Wafer handling challenges (thin wafers / thick wafers / non-Silicon wafers etc.)
- New challenges in handling SiC / GaN wafers
- Testing of chiplets
- Testing on substrates
- Advanced probing solutions
- Advances in metrology tools
- System level test on wafer level, challenges and solutions
- Improving cost of ownership and cost of test
- Test Synergies - steps forward with cooperations
- Semiautomatic wafer probing solutions
- Kryo-probing solutions
- Wafer testing with gas

**You are interested in giving a presentation on one of these subjects?  
Please do not hesitate to contact us via e-mail [info@is-test.com](mailto:info@is-test.com) or phone!**